

Full Wafer Test System

Single Touchdown High Volume Production Test Solution



* Shown with a dual chuck prober, dual FOUP loader and two independent FOX-1P test systems

SYSTEM BENEFITS

- Enables High Throughput, Single Touchdown, Full Wafer Production Testing
 - Capable of simultaneously testing up to 16,000 die in a single wafer touchdown
 - Resource configurable up to 16,384 "Universal Channels" each programmable as an I/O, Clock, Pin Parametric Measurement Unit (PPMU) or Device Power Supply (DPS)
 - Software-enabled per site flexibility to support small and large device pin count test needs
- Comprehensive functional and parametric test capabilities
 - Deep functional pattern data and capture memory optimized for BIST/DFT testing
 - Per channel PMU for per site parametric testing
 - Individual channel over-current protection to protect wafers and probe cards
- Configured for high volume production
 - Compatible with industry standard probers and probe cards
 - Available as an integrated test cell with prober, probe cards and 16,384 channel probe I/F
 - Configurable as a single or dual system integrated test cell

"Changing the Way ICs Are Tested"

STEM CERTIFICANCE OF THE CONTROL OF

